



## Final Product Change Notification

202306055F01 : NVT4857UK New BOM Qualification at ASEK

**Note:** This notice is NXP Company Proprietary.

**Issue Date:** Jul 12, 2023 **Effective date:** Oct 10, 2023

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### Management summary

Changing of repassivation from PI to PBO on NVT4857UK at ASEK due to supplier discontinuation.

### Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware <input type="checkbox"/> Other				

## PCN Overview

### Description

Changing of repassivation from PI to PBO on NVT4857UK at ASEK due to supplier discontinuation.  
Repassivation change before: I-8124ER1, and change after is: HD8820

UBM change before: Ti/NiV/Cu and change after is: Ti/Cu/Cu

It should be noted that the above configuration is a current standard and is in high volume manufacturing.

Note: A datasheet correction will be occurring. Package outline drawing (PoD) of the NVT4857UK was

renamed to SOT1397-10. Included in this update is a correction to the existing datasheet in which the

ball diameter was incorrectly listed. The correct ball diameter is being updated from 260 µm to reflect an

actual 270 µm (there were no change in products ball dimension).

### Reason

Changing of repassivation from PI to PBO on NVT4857UK at ASEK due to supplier discontinuation.

### Identification of Affected Products

Top Side Marking

### Product Availability

### Sample Information

Samples are available upon request

**Production**

Planned first shipment Oct 16, 2023

**Anticipated Impact on Form, Fit, Function, Reliability or Quality**

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No Impact on form, fit, function, reliability or quality

**Data Sheet Revision**

A new datasheet will be issued

**Disposition of Old Products**

Existing inventory will be shipped until depleted

**Additional information**

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Self qualification: [view online](#)

**Timing and Logistics**

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In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Aug 11, 2023.

**Contact and Support**

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For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Orderable Part Number#	12NC	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	Product Line
NVT4857UKAZ	935304822019	NVT4857UK	SD card SDR104 voltage translator			RFS	No	BLC6